

Product Information

Electronic Protection System

Thick Film Coating, thermal cure

Bectron[®] PK 4332

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Product description

Bectron[®] PK 4332 is a one-component resin system which cures to form a very soft polyurethane duroplastic. It comprises a liquid polyol system with a dispersed solid encapsulated polyisocyanate and a pigment combination selected to provide controlled rheology including excellent thixotropic properties.

Heating the resin releases the encapsulated polyisocyanate resulting in a polyaddition reaction to give a resistant duroplastic cured material.

In contrast to the usual 2 component resin systems Bectron[®] PK 4332 is ready to use and distinguished by excellent properties and especially good environmental compatibility.

Areas of application

The cured Bectron[®] PK 4332 is a very soft duroplastic suitable for chemical, shock and vibration protection of delicate components.

Bectron[®] PK 4332 is therefore most suited for the partial or selective coating of SMD and other components groups on printed circuit boards and ceramic substrates. It is also widely used as a casting resin for electronic components and sensors, including ultrasonic types.

Properties of the cured material

The cured material displays high elasticity and strength producing excellent temperature cycling behaviour within the range of -60°C to +125°C as well as resistance to vibrations. This ensures minimal crazing even in thick layered applications.

Bectron[®] PK 4332 has excellent chemical resistance to a wide range of aggressive liquids common in automotive applications.

Bectron[®] PK 4332 has good adhesion on almost all materials used in the field of electronics. Even after several temperature cycles there is no loss of adhesion mechanical and electrical properties

Satisfies ROHS Directive

Storage

Containers filled with Bectron[®] PK 4332 should be stored at a temperature $\leq 25^{\circ}\text{C}$ and kept closed to protect the resin against humidity.

During longer storage periods of the containers, some settling of the pigments can occur and it is advisable to homogenise the resin by rotation of the containers prior to filling storage or service tanks.

Processing suggestions

Prior to processing the resin in a storage tank should again be stirred well, e.g. 10 minutes at 20 rpm. Vacuum is not needed, but a nitrogen atmosphere is advisable to protect from humidity.

Bectron[®] PK 4332 is normally applied with a dispenser or similar equipment. The lower viscosity of Bectron[®] PK 4332 allows coating of large areas of a PCB by with suitable nozzles and for potting of electronic components and sensors.

Recommended temperature for curing is:

- 80 minutes at 80°C or
- 60 minutes at 90°C

For volume production the application of infrared (IR) radiation leads to a considerable reduction of curing times, e.g. values of <1 minute are attainable.

To ensure satisfactory adhesion on the PCB surface the following should be checked:

- Use of residue-free flux
- ensure dry surfaces
- Check compatibility of the coating resin with the solder resist and solder past

Table 1 - Properties of component as supplied

Property	Condition	Value	Unit
Viscosity, DIN 53019	D=15 s ⁻¹ , 23°C	5.500 ± 1.000	mPas
Density, DIN EN ISO 2811-2	23°C	1,05 ± 0,03	g/cm ³
Shelf life	23°C	7	months

Table 2 - Gel-time, curing conditions

Property	Value	Value	Unit
Temperature	80	90	°C
Gel-time	12,5 ± 2,5		min
Curing	80 ± 10	60 ± 5	min

Table 3 - Thermal properties of cured compound

Property	Condition	Value	Unit
Coefficient of thermal expansion, Beck Test M 56	-20°C to + 90°C	200·10 ⁻⁶	K ⁻¹
Thermal conductivity, DIN 52616	23°C	0,18 ± 0,02	W/mK

Table 4 - Mechanical properties of cured compound

Property	Condition	Value	Unit
Glass transition temperature, IEC 61006	-	-50	°C
Shore hardness, ISO 868	23°C	35 ± 10	Shore A

Table 5 - Dielectric properties of cured compound

Property	Condition	Value	Unit
Volume resistivity, IEC 60455 part 2 After water immersion	Initial value	10 ¹³	Ω • cm
	7days	10 ¹¹	Ω • cm
Dielectric strength, IEC 60455 part 2	23°C	22	kV/mm
Tracking IEC 60112	Solution B	CTI 600 M	

Table 6 - Chemical properties of cured compound

Property	Condition	Value	Unit
Water absorption Beck test 9, Method 1	24h / 23°C	131	mg

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